

Title (en)  
METALLISED FILM FOR SHEET CONTACTING

Title (de)  
METALLISIERTE FOLIE ZUR FLÄCHIGEN KONTAKTIERUNG

Title (fr)  
FEUILLE METALLISEE POUR ETABLISSEMENT DE CONTACT EN NAPPE

Publication  
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Application  
**EP 05815728 A 20051121**

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Abstract (en)  
[origin: WO2006058850A1] The invention relates to a method for contacting at least one electrical contact surface (1) on a surface of a substrate (2) and/or at least one component (3) arranged on the substrate (2), especially a semiconductor chip. Said method comprises the following steps: at least one insulating film (4) consisting of an electrically insulating plastic material is laminated, under a vacuum, onto the surfaces of the substrate (2) and the component comprising the contact surface (1); and the contact surface (1) to be contacted on the surfaces is bared by opening a window (6) in the insulating film (4). The invention is characterised by sheet contacting the bared contact surface (1) with at least one metallisation (5) on an insulating film (4).

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